PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	ADG/22/13572
1.3 Title of PCN	L99PM62GXP / L99PM62GXPTR (UK19, ST Singapore Fab): Package Bill Of Material Upgrade
1.4 Product Category	L99PM62GXP / L99PM62GXPTR (Singapore silicon Fab)
1.5 Issue date	2022-07-26

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Francesco MACINA
2.1.2 Marketing Manager	Giovanni Luca TORRISI
2.1.3 Quality Manager	Marcello Donato MENCHISE

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	ST Muar - Malaysia

4. Description of change

	Old	**New**
4.1 Description	Au wires 1.3 mils Mold compound Hitachi CEL 9240	Cu wires 1.2mils Mold compound Sumitomo G700LS Leadframe finishing in rough copper
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	Company Roadmap and Quality Improvement
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Good Codes

7. Timing / schedule

7.1 Date of qualification results	2022-07-14
7.2 Intended start of delivery	2022-11-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13572 Validation.zip		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2022-07-26

9. Attachments (additional documentations)

13572 Public product.pdf
13572 Validation.zip
13572 Details.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	L99PM62GXPTR	

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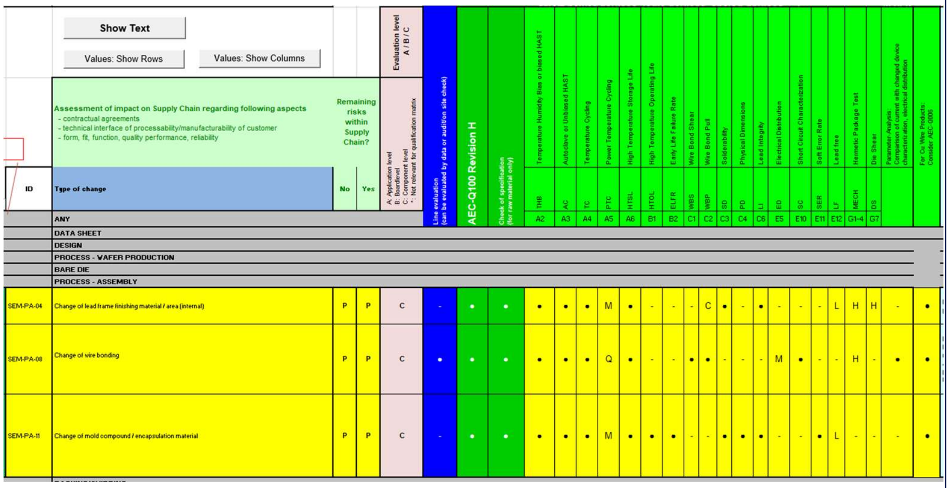
PRODUCT/PROCESS CHANGE NOTIFICATION

TITLE	**L99PM62GXP / L99PM62GXPTR (UK19, ST Singapore Fab): Package Bill Of Material Upgrade**
IMPACTED PRODUCTS	ST line UK19 diffused in ST Singapore Fab in BCD5 technology and assembled in PowerSSO36 package, currently adopting gold 1.3mil wires
LINKED TO PCN	PCN ADG/21/12627 - L99PM62GXP / L99PM62GXPTR (UK19): Package Bill of Material Upgrade (UK19 diffused in ST Agrate Fab)
MANUFACTURING STEP	Assembly
INVOLVED PLANT	ST Muar Plant (Malaysia)
CHANGE REASON	Company roadmap and quality improvement
CHANGE DESCRIPTION	Package Bill Of Material upgrade based on following conversions: - gold wires 1.3mil diameter converted to copper 1.2 mils; - mold compound Hitachi CEL 9240 converted to Sumitomo G700LS - leadframe finishing converted to rough copper
TRACEABILITY	Internal Traceability and new Finished Good codes (internal part number)

VALIDATION	Validation has been performed according to ZVEI Guidelines for Automotive Changes, e.g. AEC Q100 and Q006:



ID	Assessment of impact on Supply Chain regarding following aspects - contractual agreements - technical interface of processability/manufacturability of customer - form, fit, function, quality performance, reliability Type of change	Remaining risks within Supply Chain? No	Remaining risks within Supply Chain? Yes	Evaluation level A / B / C A: Application level B: Boardlevel C: Component level *: Not relevant for qualification matrix	Line evaluation (can be evaluated by data or audit/on site check)	AEC-Q100 Revision H	Check of specification (for raw material only)	Temperature Humidity Bias or biased HAST THB A2	Autoclave or Unbiased HAST AC A3	Temperature Cycling TC A4	Power Temperature Cycling PTC A5	High Temperature Storage Life HTSL A6	High Temperature Operating Life HTOL B1	Early Life Failure Rate ELFR B2	Wire Bond Shear WBS C1	Wire Bond Pull WBP C2	Solderability SD C3	Physical Dimensions PD C4	Lead Integrity LI C6	Electrical Distribution ED E5	Short Circuit Characterization SC E10	Soft Error Rate SER E11	Lead free LF E12	Hermetic Package Test MECH G1-4	Die Shear DS G7	Parameter Analysis: Comparison of current with changed device characterization, electrical distribution	For Cu Wire Products: Consider AEC-Q006
	ANY																										
	DATA SHEET																										
	DESIGN																										
	PROCESS - WAFER PRODUCTION																										
	BARE DIE																										
	PROCESS - ASSEMBLY																										
SEM-PA-04	Change of lead frame finishing material / area (internal)	P	P	C	-	●	●	●	●	●	M	●	-	-	-	C	●	-	●	-	-	-	L	H	H	-	●
SEM-PA-08	Change of wire bonding	P	P	C	●	●	●	●	●	●	Q	●	-	-	●	●	-	-	-	M	●	-	-	H	-	●	●
SEM-PA-11	Change of mold compound / encapsulation material	P	P	C	-	●	●	●	●	●	M	●	●	●	-	-	●	●	●	-	-	●	L	-	-	-	●

CURRENT PRODUCTS	Current products will be replaced by the new version with the upgraded Bill Of Material (wires, mold compound, leadframe finishing).
REPORTS	13572 Validation.zip that includes: - Reliability Report on TV Diffused in ST Singapore Fab (UK40)

Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : L99PM62GXP / L99PM62GXPTR (UK19, ST Singapore Fab): Package Bill Of Material Upgrade

PCN Reference : ADG/22/13572

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

L99PM62GXP	**L99PM62GXPTR**	

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